

B<sub>1</sub> end  
39. **(Once Amended)** The composition according to claim 38, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).

46. **(New)** The composition according to claim 38, wherein the mineral acid is selected from a group consisting of HCl, HNO<sub>3</sub>, H<sub>2</sub>SO<sub>4</sub>, H<sub>3</sub>PO<sub>4</sub>, and HF.

47. **(New)** An etching composition, the composition comprising a mineral acid, a peroxide, and deionized water at a ratio in a range of about 1:1:35 (mineral acid:peroxide:deionized water) to about 1:1:5 (mineral acid:peroxide:deionized water), wherein the composition has an etch rate greater than about 1000 Å/minute for cobalt.

B<sub>2</sub>  
48. **(New)** The etching composition according to claim 47, wherein the mineral acid is HCl.

49. **(New)** The etching composition according to claim 47, wherein the peroxide is hydrogen peroxide.

50. **(New)** The composition according to claim 47, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).

51. **(New)** The composition according to claim 47, wherein the composition has an etch rate of about 50 Å/minute to about 250 Å/minute for metal nitride.

52. **(New)** An etching composition, the composition comprising a mineral acid, a peroxide, and deionized water at a ratio in a range of about 1:1:35 (mineral acid:peroxide:deionized water) to about 1:1:5 (mineral acid:peroxide:deionized water), wherein the composition has an etch rate of about 50 Å/minute to about 250 Å/minute for metal nitride.

53. (New) The etching composition according to claim 52, wherein the mineral acid is HCl.

54. (New) The etching composition according to claim 52, wherein the peroxide is hydrogen peroxide.

55. (New) The composition according to claim 52, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).

56. (New) An etching composition, the composition consisting essentially of a mineral acid, a peroxide, and deionized water.

57. (New) The composition according to claim 56, wherein the mineral acid is HCl and the peroxide is hydrogen peroxide.

58. (New) The composition according to claim 57, wherein the composition comprises a ratio in a range of about 1:1:35 (mineral acid:peroxide:deionized water) to about 1:1:5 (mineral acid:peroxide:deionized water).

59. (New) The composition according to claim 58, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).

60. (New) The composition according to claim 56, wherein the mineral acid is selected from a group consisting of HCl, HNO<sub>3</sub>, H<sub>2</sub>SO<sub>4</sub>, H<sub>3</sub>PO<sub>4</sub>, and HF.